

## ANNEX

In Annex III, entry 15 is replaced by the following:

15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Applies to categories 8, 9 and 11 and expires on: — 21 July 2021 for categories 8 and 9 other than in vitro diagnostic medical devices and industrial monitoring and control instruments; — 21 July 2023 for category 8 in vitro diagnostic medical devices; — 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11.
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: — a semiconductor technology node of 90 nm or larger; — a single die of 300 mm <sup>2</sup> or larger in any semiconductor technology node; — stacked die packages with die of 300 mm <sup>2</sup> or larger, or silicon interposers of 300 mm <sup>2</sup> or larger.	Applies to categories 1 to 7 and 10 and expires on 21 July 2021.